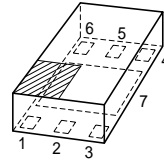


The BGA619 Silicon-Germanium High IP3 Low Noise Amplifier in PCS Receiver Applications

Features

- Easy-to-use LNA MMIC in 70 GHz f_t SiGe technology
- Tiny „Green“ P-TSLP-7-1 package (no Lead or Halogen compounds)
- Low external component count
- Integrated output DC blocking capacitor, integrated RF choke on internal bias network
- Three gain steps
- Power off function
- High IP3 in all modes



P-TSLP-7-1

Applications

- Low Noise Amplifier for 1900 MHz PCS wireless frontends (CDMA 2000).

Introduction

The BGA619 is an easy-to-use, low-cost **Low Noise Amplifier (LNA) MMIC** designed for use in today's PCS systems which require excellent linearity in each of several gain step modes. Based on Infineon's cost-effective 70 GHz f_T Silicon-Germanium (SiGe) B7HF bipolar process technology, the BGA619 offers a 1.5 dB noise figure and 14.9 dB of gain at 1.96 GHz with a current consumption of 6.5 mA in high gain mode. BGA619 offers impressive IIP3 performance of 7 dBm in High Gain mode, particularly for a three-gain step, low-cost, integrated MMIC.

The new LNA incorporates a 50 Ω pre-matched output with an integrated output DC blocking capacitor. The input is pre-matched, requiring an external DC blocking capacitor. An integrated, on-chip inductor eliminates the need for an external RF choke on the voltage supply pin. The operating mode of the device is determined by the voltage at the GS-pin. An integrated on/off feature provides for low power consumption and increased stand by time for PCS cellular handsets.

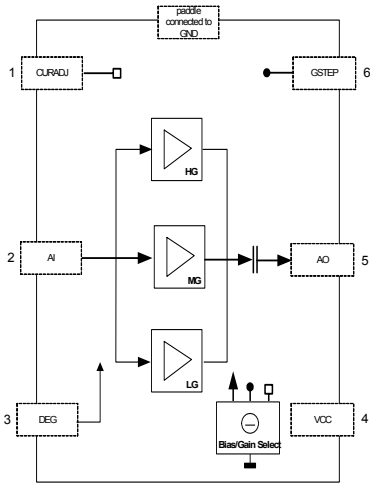


Figure 1 BGA619's Equivalent Circuit.

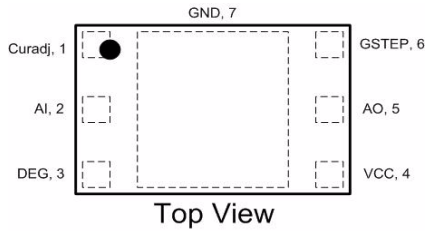


Figure 2 Pin Connections

Overview

The BGA619 has three gain steps and one off-mode which are used in PCS-band applications:

- High Gain Mode
- Mid Gain Mode
- Low Gain Mode
- OFF Mode

Mode selection is performed by applying a voltage to pin 6 (GSTEP) as described in [Table 1](#). The source that generates these mode-select voltages should be able to source or sink current. Please refer to the BGA619 datasheet for the maximum values of mode control current.

Table 1 Switching Modes for Gain Steps

| Gain Mode | Gain Step Input Voltage [V] | | Current into GS-pin [μA] |
|-----------|-----------------------------|-----|--------------------------|
| | Min | Max | typ |
| High Gain | 2.2 | 2.4 | 65 |
| Mid Gain | 1.6 | 1.8 | 40 |
| Low Gain | 0.9 | 1.1 | 8 |
| OFF | 0.0 | 0.3 | -35 |

The next table shows the measured performance of each of these gain modes. All measurement values presented in this application note include losses of both PCB and connectors - in other words, the reference planes used for measurements are the PCB's RF SMA connectors. Noise figure and gain results shown here would improve by 0.2 - 0.3 dB compared to the values shown if PCB losses were extracted.

All measurements are performed at 1960 MHz and at a typical supply voltage of 2.78 V.

Table 2 Performance Overview

| Parameter | High Gain Mode | Mid Gain Mode | Low Gain Mode |
|---|---------------------|-----------------------|----------------------|
| Supply voltage | 2.78 V | 2.78 V | 2.78 V |
| Supply current | 6.5 mA | 4.5 mA | 2.9 mA |
| Gain | 14.9 dB | 2.2 dB | -9.5 dB |
| Noise Figure | 1.5 dB | 8 dB | 16 dB |
| Input return loss | 10.5 dB | 8.5 dB | 12.5 dB |
| Output return loss | 11.5 dB | 13 dB | 13 dB |
| Reverse Isolation | 25 dB | 21 dB | 23 dB |
| Input 3 rd order intercept point | 7 dBm ¹⁾ | 6.5 dBm ²⁾ | 15 dBm ³⁾ |

¹⁾ -30 dBm per tone, f1=1950 MHz, Δf = 1 MHz

²⁾ -27 dBm per tone, f1=1950 MHz, Δf = 1 MHz

³⁾ -15 dBm per tone, f1=1950 MHz, Δf = 1 MHz

Board Configuration

The circuit in [Figure 3](#) shows the board configuration for BGA619 LNA. The Bill of materials for the application board can be found in [Table 3](#).

Figure 3 PCB board configuration

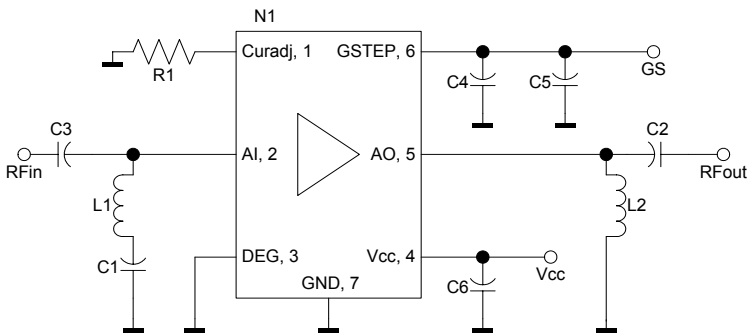


Table 3 Bill of material

| Name | Value | Package | Manufacturer | Function |
|-------------|--------------|----------------|---------------------|--|
| R1 | 15 kΩ | 0402 | various | bias resistance; set device current |
| L1 | 3.3 nH | 0402 | various | LF trap & input matching; L1 and C1 provide low-frequency trap to increase input IP3 |
| L2 | 4.7 nH | 0402 | various | output matching |
| C1 | 10 nF | 0402 | various | LF trap for IP3 enhancement |
| C2 | 10 pF | 0402 | various | output DC block; optional because DC block is integrated |
| C3 | 10 pF | 0402 | various | input DC block |
| C4 | 10p | 0402 | various | control voltage filtering - OPTIONAL, depends on actual user implementation |
| C5 | 1 nF | 0402 | various | control voltage filtering - OPTIONAL, depends on actual user implementation |
| C6 | 1 nF | 0402 | various | supply filtering, depends on actual user implementation |
| C7 | | 0402 | various | supply filtering - OPTIONAL, depends on actual user implementation |
| N1 | BGA619 | P-TSLP-7-1 | Infineon | SiGe LNA with gain-steps |

The application board is made of 3 layer FR4 material (see [Figure 4](#)). The top view can be seen in [Figure 5](#) and the bottom view in [Figure 6](#). Pictures of the board can be found in [Figure 7](#) (complete board) and [Figure 8](#) (close-in photograph, where BGA619 and surrounding elements can be found in detail).

Figure 4 Application board; board construction

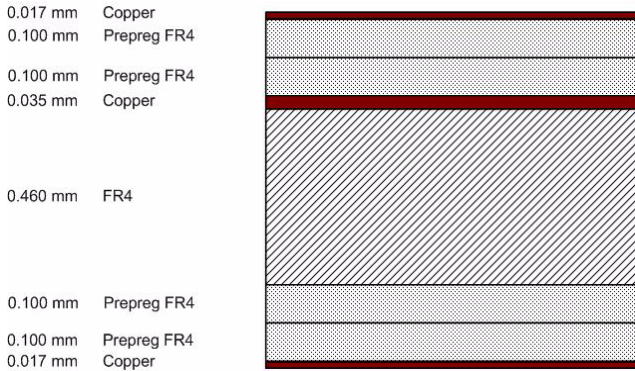


Figure 5 Application board; top view

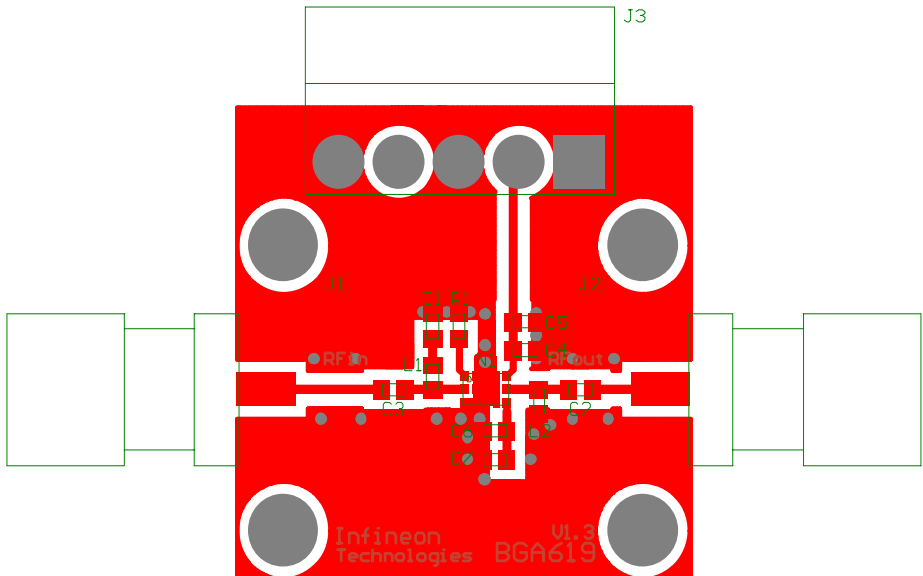


Figure 6 Application board; bottom view

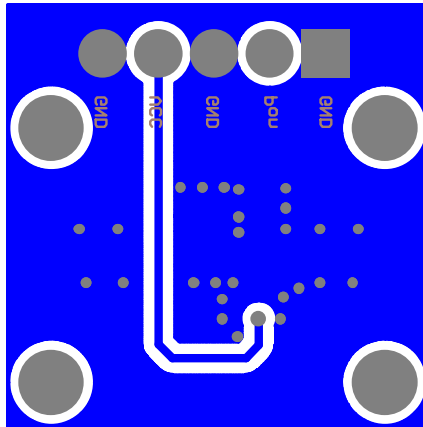


Figure 7 Foto of Application board

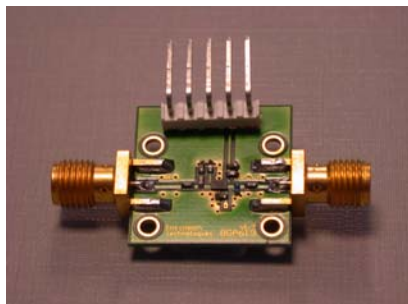
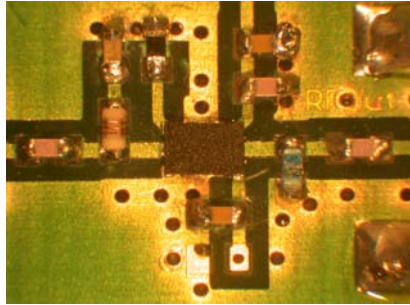


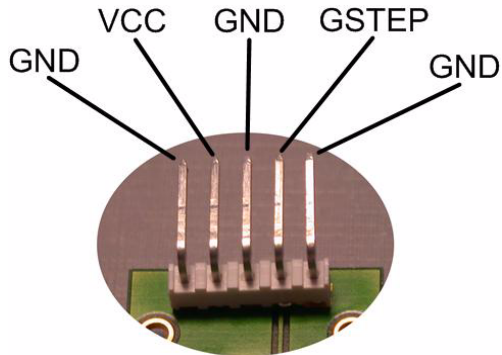
Figure 8 Scanned image of PCB, Close-In shot



The power supply connector

Figure 9 shows the pinning of the power supply connector needed for powering the test board.

Figure 9 Power Supply Connector



For measurement graphs please refer to the next pages.

Figure 10 Noise Figure High Gain Mode

Noise Figure $NF = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 6.5mA$

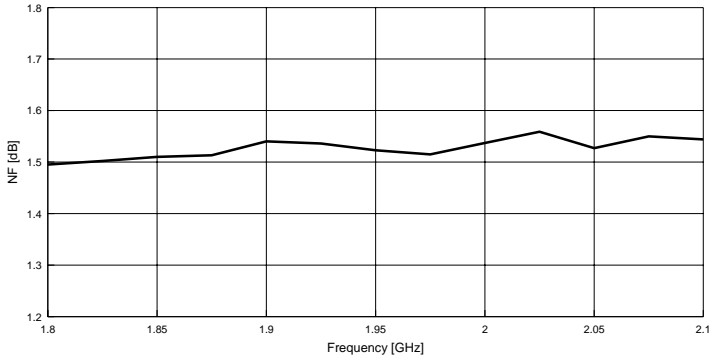


Figure 11 Gain High Gain Mode

Power Gain $|S_{21}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 6.5mA$

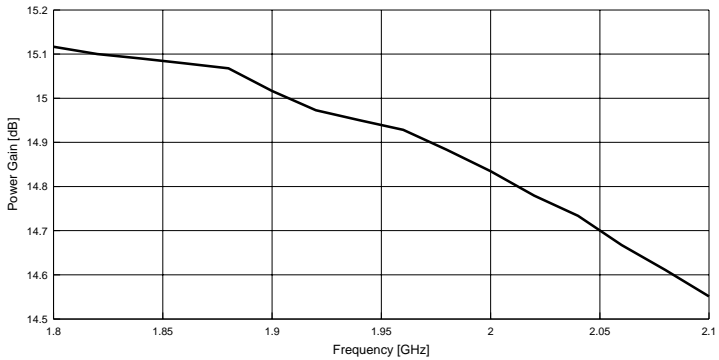


Figure 12 Return Loss High Gain Mode

Matching $|S_{11}|, |S_{22}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 6.5mA$

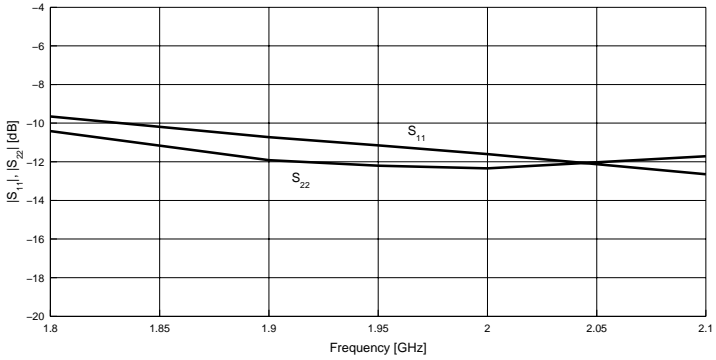


Figure 13 Reverse Isolation High Gain Mode

Reverse Isolation $|S_{12}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 6.5mA$

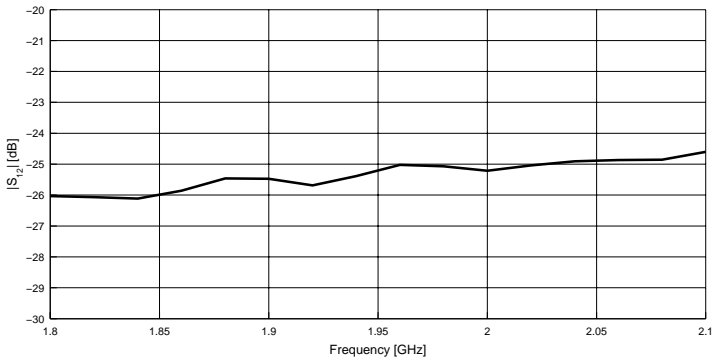


Figure 14 Noise Figure Mid Gain Mode

Noise Figure $NF = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 4.5mA$

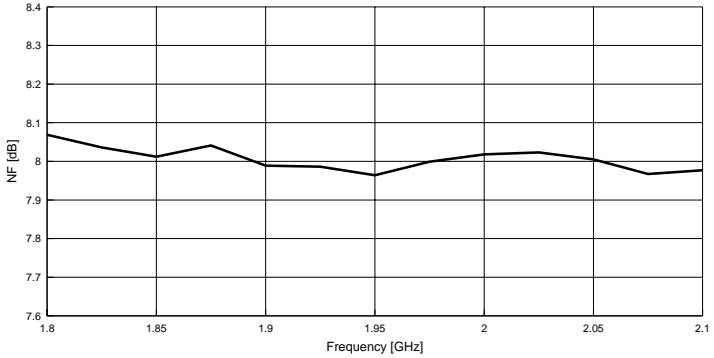


Figure 15 Gain Mid Gain Mode

Power Gain $|S_{21}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 4.5mA$

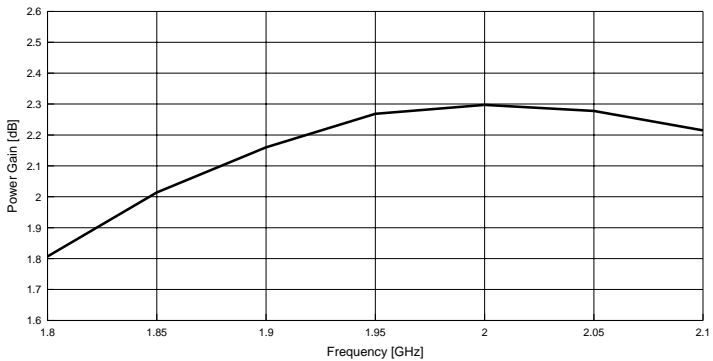


Figure 16 Return Loss Mid Gain Mode

Matching $|S_{11}|, |S_{22}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 4.5mA$

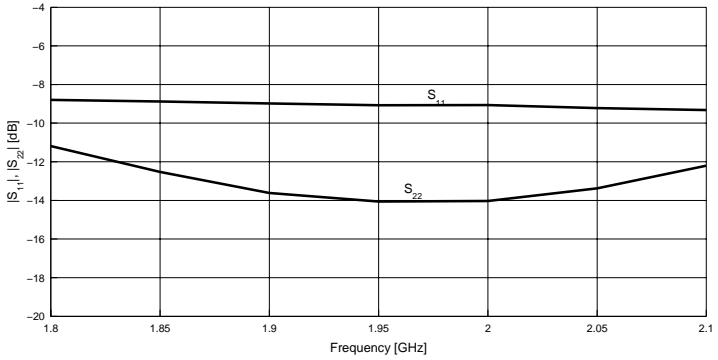


Figure 17 Reverse Isolation Mid Gain Mode

Reverse Isolation $|S_{12}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 4.5mA$

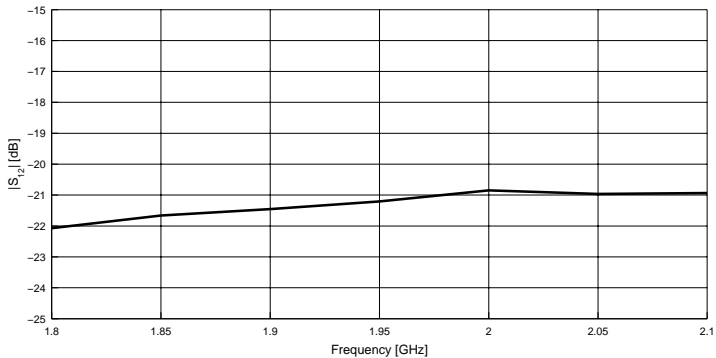


Figure 18 Noise Figure Low Gain Mode

Noise Figure $NF = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 2.9mA$

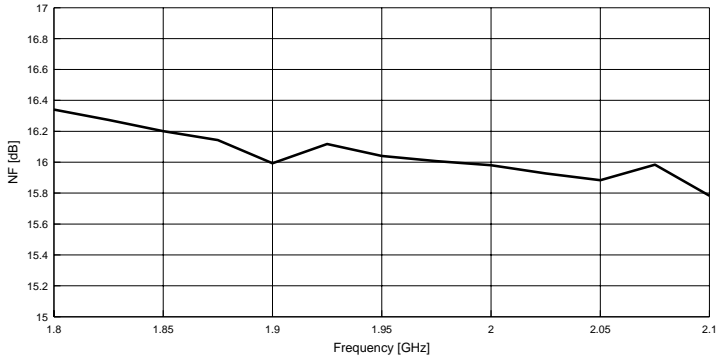


Figure 19 Gain Low Gain Mode

Power Gain $|S_{21}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 2.9mA$

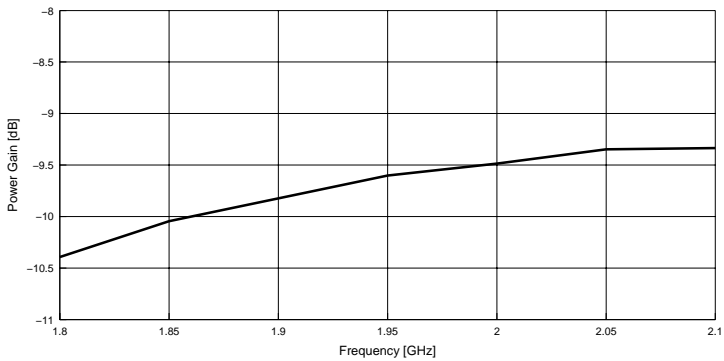


Figure 20 Return Loss Low Gain Mode

Matching $|S_{11}|, |S_{22}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 2.9mA$

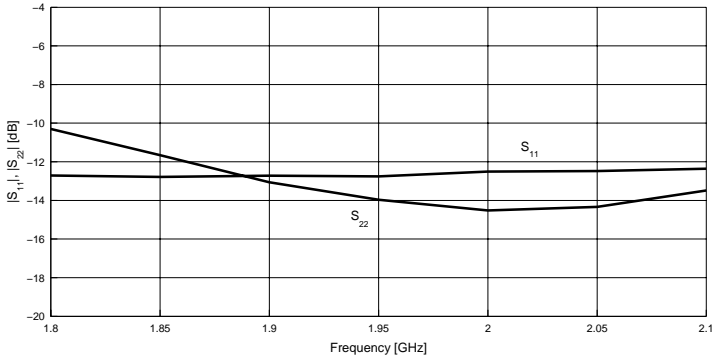
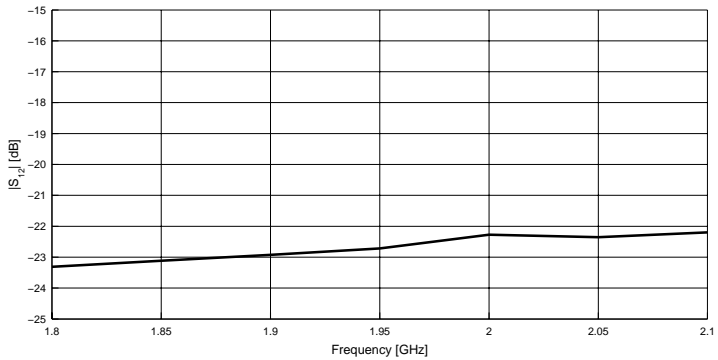


Figure 21 Reverse Isolation Low Gain Mode

Reverse Isolation $|S_{12}| = f(f)$
 $V_{CC} = 2.78V, I_{CC} = 2.9mA$



AN081

Revision History: 2004-04-19

v1.0

Previous Version:

| Page | Subjects (major changes since last revision) |
|------|--|
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